

TPS62180EVM-581 Evaluation Module

This user's guide describes the characteristics, operation, and use of TI's TPS62180 evaluation module (EVM). The TPS62180EVM-581 (PWR581-001) facilitates the evaluation of the TPS62180 6-A, 2-phase buck converter. The EVM outputs a 3.3-V output voltage from input voltages between 4 V and 15 V. The TPS62180 features Automatic Efficiency Enhancement (AEE^{TM}) to deliver efficiencies in excess of 90% across the load current range. The small solution size (99 mm²) and low profile possible enable a very dense power solution in tablets, Solid State Drives (SSDs), and other portable devices. This user's guide includes setup instructions for the hardware, a printed-circuit board layout for the EVM, a schematic diagram, a bill of materials (BOM), and test results for the EVM.

Contents

1	Introduction	1
2	Setup	3
3	TPS62180EVM-581 Test Results	4
4	Board Layout	5
5	Schematic and Bill of Materials	8

List of Figures

1	Thermal Performance (V _{IN} = 15 V, Load = 6 A)	4
2	Loop Measurement (V_{IN} = 12 V, Load = 6 A, 50- Ω resistor added in series with R1)	4
3	Assembly Layer	5
4	Top Silk Layer	5
5	Top Layer	6
6	Internal Layer 1	6
7	Internal Layer 2	7
8	Bottom Layer	7
9	TPS62180EVM-581 Schematic	8

List of Tables

1	Performance Specification Summary	2
2	TPS62180EVM-581 Bill of Materials	9

1 Introduction

The TPS62180 is a 6-A, dual-phase, synchronous, step-down converter in a 2×3 -mm, WCSP package. Both fixed and adjustable output voltage units are available.

AEE is a trademark of Texas Instruments.



Introduction

1.1 Performance Specification

Table 1 provides a summary of the TPS62180EVM-581 performance specifications. All specifications are given for an ambient temperature of 25°C.

Specification	Test Conditions	Min	Тур	Max	Unit
Input voltage		4		15	V
Output voltage setpoint			3.3		V
Output current		0		6	А
Soft-start time	Ramp time of V _{OUT}		825		μs

Table 1. Performance Specification Summary

1.2 Modifications

The printed-circuit board (PCB) for this EVM is designed to accommodate the fixed output voltage version of the integrated circuit (IC). Additional input and output capacitors can also be added. A lower profile inductor may also be used to reduce the total solution height. Finally, the input voltage at which the IC turns on can be adjusted with two resistors.

1.2.1 Fixed Output Voltage Operation

U1 can be replaced with the fixed output voltage version of the IC for evaluation. For fixed output voltage version operation, replace R2 with a 0- Ω resistor and remove R1.

1.2.2 Input and Output Capacitors

C13 and C14 are provided for additional input capacitors. These capacitors are not required for proper operation but can be used to reduce the input voltage ripple.

C7, C8, C9, C10, C11, and C12 are provided for additional output capacitors. These capacitors are not required for proper operation but can be used to reduce the output voltage ripple and to improve the load transient response. The total output capacitance must remain within the recommended range in the TPS62180 data sheet (SLVSBB8) for proper operation.

1.2.3 Lower Profile Solutions

The TPS62180EVM-581 supports modifications to achieve a lower total solution profile (height). The current EVM gives a maximum height of 2.1 mm. To obtain a lower profile solution, replace both inductors L1 and L2 with a suitable inductor of lower height. An option is the DFE252012P series from Toko which has a maximum profile of 1.2 mm. These inductors fit well on the existing pads for L1 and L2.

1.2.4 Configurable Enable Threshold Voltage

With JP1 removed, R4 and R5 can be installed to set a user-selectable input voltage at which the IC turns on. See the equations in the data sheet for details of calculating the resistor values.



2 Setup

This section describes how to properly use the TPS62180EVM-581.

2.1 Input/Output Connector Descriptions

J1 – VIN	Positive input connection from the input supply for the EVM
J2 – S+/S–	Input voltage sense connections. Measure the input voltage at this point.
J3 – GND	Return connection from the input supply for the EVM
J4 – VOUT	Output voltage connection
J5 – S+/S–	Output voltage sense connections. Measure the output voltage at this point.
J6 – GND	Output return connection
J7 – PG/GND	The PG output appears on pin 1 of this header with a convenient ground on pin 2
J8 – SS/TR/GND	The SS/TR pin voltage appears on pin 2 of this header with a convenient ground on pin 1 $$
JP1 – EN	EN pin input jumper. Place the supplied jumper across ON and EN to turn on the IC. Place the jumper across OFF and EN to turn off the IC. Remove the jumper to set a configurable enable threshold voltage with R4 and R5.
JP2 – PG Pullup Voltage	PG pin pullup voltage jumper. Place the supplied jumper on JP2 to connect the PG pin pullup resistor to the output voltage. Alternatively, the jumper can be removed and a different voltage can be supplied on pin 1 to pull up the PG pin to a different level. This externally applied voltage must remain below 7 V.

2.2 Setup

To operate the EVM, set jumpers JP1 and JP2 to the desired positions per Section 2.1. Connect the input supply to J1 and J3 and connect the load to J4 and J6.



TPS62180EVM-581 Test Results

3 TPS62180EVM-581 Test Results

The TPS62180EVM-581 was used to take the data in the TPS62180 data sheet (SLVSBB8). See the device data sheet for the performance of this EVM.

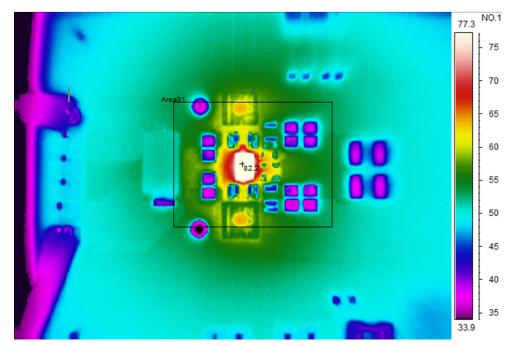


Figure 1. Thermal Performance ($V_{IN} = 15 V$, Load = 6 A)

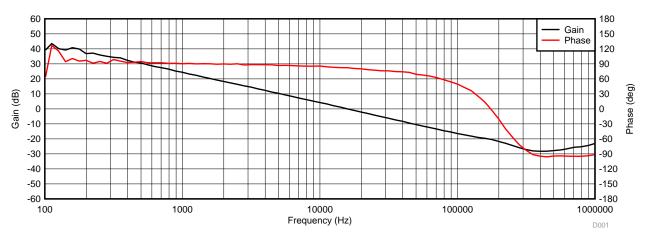


Figure 2. Loop Measurement (V_{IN} = 12 V, Load = 6 A, 50- Ω resistor added in series with R1)



4 Board Layout

This section provides the TPS62180EVM-581 board layout and illustrations. The Gerbers are available on the EVM product page: <u>TPS62180EVM-581</u>. Rev. B of the PCB just filled the vias under U1 to improve manufacturability. No copper changes were made from Rev. A.

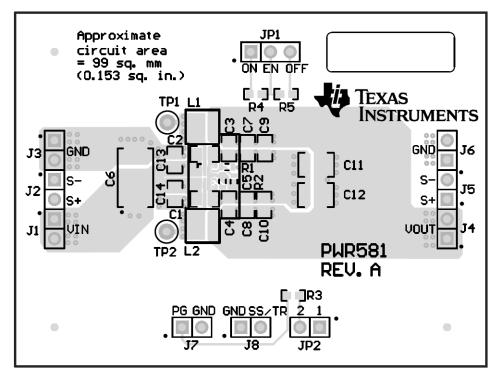


Figure 3. Assembly Layer

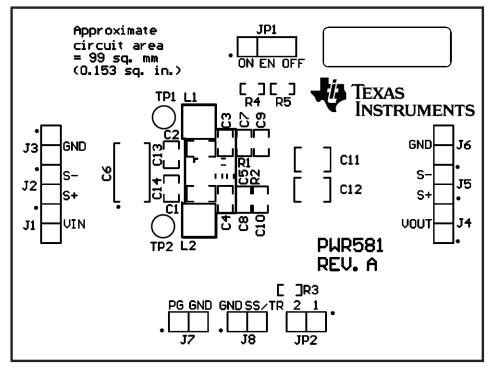


Figure 4. Top Silk Layer



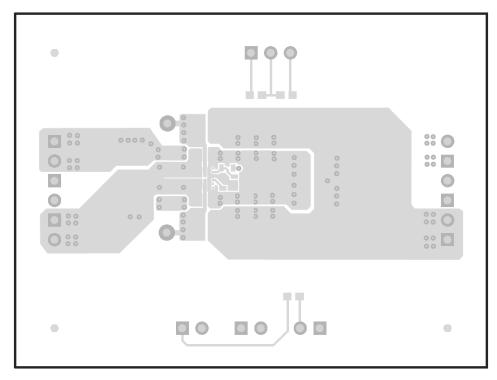


Figure 5. Top Layer

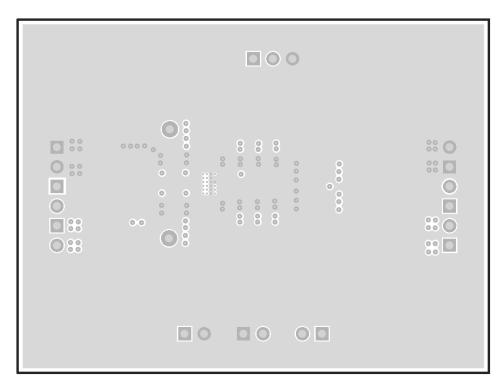


Figure 6. Internal Layer 1



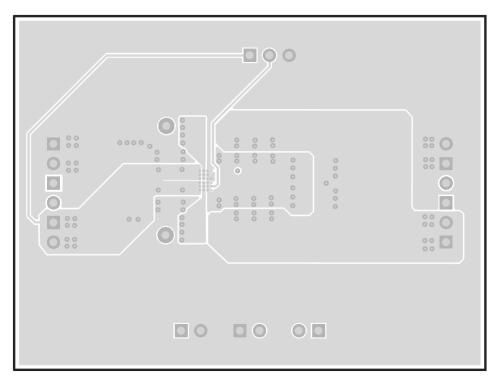


Figure 7. Internal Layer 2

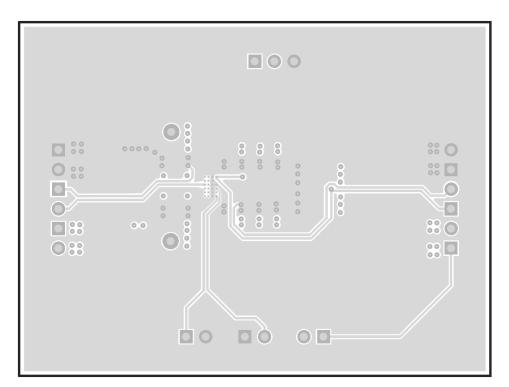


Figure 8. Bottom Layer

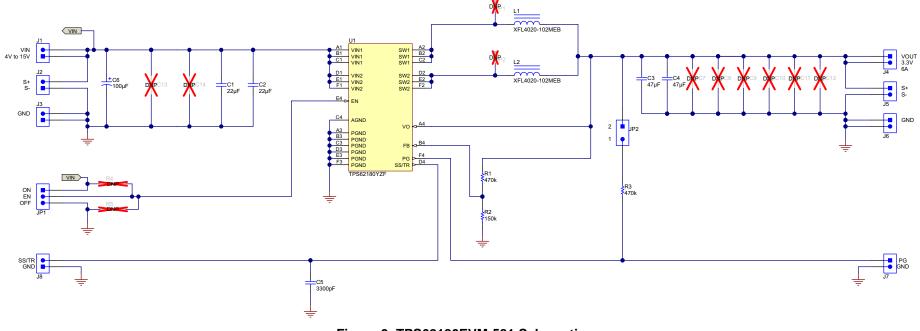


5 Schematic and Bill of Materials

This section provides the TPS62180EVM-581 schematic and bill of materials.

5.1 Schematic

Figure 9 illustrates the TPS62180EVM-581 schematic.





Schematic and Bill of Materials

5.2 Bill of Materials

Table 2 lists the BOM for this EVM.

Quantity	Ref Des	Value	Description	Size	Part Number	Manufacturer
2	C1, C2	22uF	CAP, CERM, 22uF, 25V, +/-20%, X5R, 0805	0805	GRM21BR61E226ME44L	MuRata
2	C3, C4	47uF	CAP, CERM, 47uF, 10V, +/-20%, X5R, 0805	0805	GRM21BR61A476ME15L	MuRata
1	C5	3300pF	CAP, CERM, 3300pF, 25V, +/-10%, X7R, 0603	0603	GRM188R71E332KA01D	MuRata
1	C6	100uF	CAP, TA, 100uF, 20V, +/-10%, 0.5 ohm, SMD	7343-43	293D107X9020E2TE3	Vishay-Sprague
2	L1, L2	1uH	Inductor, Shielded, Composite, 1uH, 5.4A, 0.01 ohm, SMD	4x2x4mm	XFL4020-102MEB	Coilcraft
2	R1, R3	470k	RES, 470k ohm, 1%, 0.1W, 0603	0603	RC0603FR-07470KL	Yageo America
1	R2	150k	RES, 150k ohm, 1%, 0.1W, 0603	0603	RC0603FR-07150KL	Yageo America
1	U1	TPS62180 ⁽¹⁾	4 - 15V, 6A, 2-Phase Step-Down Converter	2x3mm	TPS62180YZF	Texas Instruments

Table 2. TPS62180EVM-581 Bill of Materials

⁽¹⁾ The TPS62180EVM-581 may be populated with TPS62180 (U1) devices that do not contain the correct top-side markings on the top of the device itself. These devices are still fully-tested TPS62180 devices and meet the specified electrical characteristics of the data sheet.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		Applications	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	TI E2E Community	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconne	ctivity	

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2014, Texas Instruments Incorporated